

ABSTRACT

A test system for a semiconductor device couples the device to the back side of a circuit board, thereby allowing the device to be tested under actual operating conditions while providing adequate clearance around the device to accommodate automatic handling equipment, and also reducing signal delay and distortion. A system in accordance with the present invention includes a circuit board having circuitry adapted to provide an actual operating environment for the semiconductor device, as for example, a low cost mother board for testing memory devices. The device is coupled to the back side of the circuit board through test terminals formed on the back side of the board. An interface board can be used to correct the pin arrangements, which are reversed because they protrude from the back side of the board, and to compensate for the environmental differences caused by use of sockets and additional equipment on the interface board.

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